Unit: mm

TOSHIBA Field Effect Transistor Silicon N Channel MOS Type  $(\pi$ -MOSIII<sup>.5</sup>)

## 2SK1486

# Chopper Regulator, DC-DC Converter and Motor Drive Applications

• Low drain—source ON resistance :  $RDS (ON) = 0.08 \Omega (typ.)$ • High forward transfer admittance :  $|Y_{fs}| = 14 S (typ.)$ 

• Low leakage current  $: I_{DSS} = 300 \,\mu\text{A} \,(\text{max}) \,(V_{DS} = 300 \,\text{V})$ 

• Enhancement mode :  $V_{th} = 2.0 \sim 4.0 \text{ V (Vps} = 10 \text{ V, Ip} = 1 \text{ mA})$ 

### Absolute Maximum Ratings (Ta = 25°C)

Characteris	stics	Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	300	V	
Drain-gate voltage (Ro	<sub>SS</sub> = 20 kΩ)	$V_{DGR}$	300	V	
Gate-source voltage		$V_{GSS}$	±30	V	
Drain current	DC (Note 1)	ΙD	32	Α	
	Pulse (Note 1)	I <sub>DP</sub>	128	A	
Drain power dissipation	n (Tc = 25°C)	P <sub>D</sub>	200	W	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

2-21F1B

Weight: 9.75 g (typ.)

**TOSHIBA** 

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings. Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/Derating Concept and Methods) and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to case	R <sub>th (ch-c)</sub>	0.625	°C / W
Thermal resistance, channel to ambient	R <sub>th (ch-a)</sub>	35.7	°C/W

Note 1: Ensure that the channel temperature does not exceed 150°C.

This transistor is an electrostatic-sensitive device.

Please handle with caution.



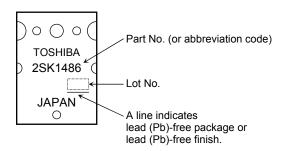
## **Electrical Characteristics (Ta = 25°C)**

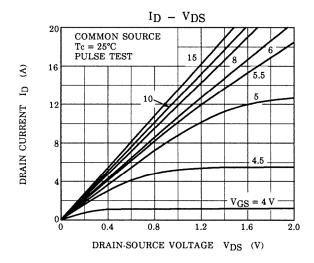
Charac	eteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage cu	rrent	I <sub>GSS</sub>	V <sub>GS</sub> = ±30 V, V <sub>DS</sub> = 0 V	_	_	±100	nA
Drain cut-off cu	rent	I <sub>DSS</sub>	V <sub>DS</sub> = 300 V, V <sub>GS</sub> = 0 V		_	300	μA
Drain-source br	eakdown voltage	V (BR) DSS	I <sub>D</sub> = 10 mA, V <sub>GS</sub> = 0 V	300	_	_	V
Gate threshold v	roltage	V <sub>th</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 1 mA	2.0	_	4.0	V
Drain-source Ol	N resistance	R <sub>DS</sub> (ON)	I <sub>D</sub> = 16 A, V <sub>GS</sub> = 10 V		0.08	0.095	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 16 A	10	14	_	S
Input capacitano	e	C <sub>iss</sub>			3500	_	
Reverse transfer	e transfer capacitance $C_{rss}$ $V_{DS} = 10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		800	_	pF
Output capacitance		Coss	1		1250	_	
T Switching time F	Rise time	t <sub>r</sub>	$V_{GS}$ $V_{OV}$ $V_{OUT}$ $V_{DD}$ $V_{DD}$ $V_{OUT}$ $V_{DD}$	_	255	_	- ns
	Turn-on time	t <sub>on</sub>		_	325	_	
	Fall time	t <sub>f</sub>		_	280	_	
	Turn-off time	t <sub>off</sub>	Duty $\leq 1\%$ , $t_{\mathbf{W}} = 10 \mu \text{s}$	_	540	_	
Total gate charge (Gate-source plus gate-drain)		Qg		_	140	_	
Gate-source charge		Q <sub>gs</sub>	$V_{DD} \approx 240 \text{ V}, V_{GS} = 10 \text{ V}, I_D = 32 \text{ A}$		60	_	nC
Gate-drain ("miller") charge		$Q_{gd}$			80	_	

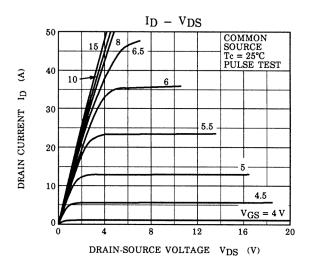
## Source-Drain Ratings and Characteristics (Ta = 25°C)

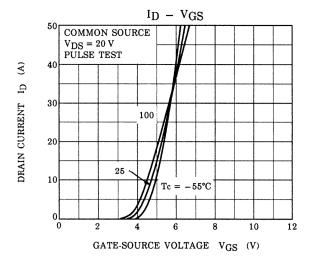
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Continuous drain reverse current (Note 1)	I <sub>DR</sub>	_	-	_	32	Α
Pulse drain reverse current (Note 1)	I <sub>DRP</sub>	_	_	_	128	Α
Forward voltage (diode)	$V_{DSF}$	I <sub>DR</sub> = 32 A, V <sub>GS</sub> = 0 V	_	_	-1.8	V
Reverse recovery time	t <sub>rr</sub>	I <sub>DR</sub> = 32 A, V <sub>GS</sub> = 0 V		615	_	ns
Reverse recovered charge	Qrr	dl <sub>DR</sub> / dt = 100 A / μs	_	6.8	_	μC

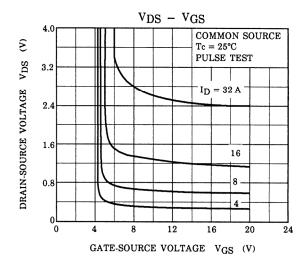
## Marking

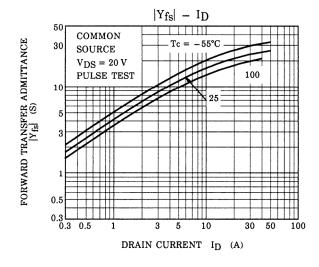


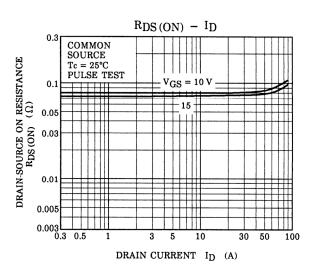


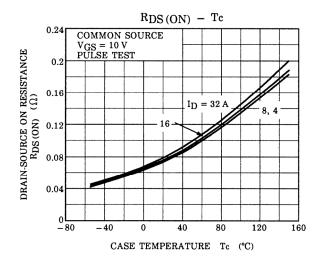


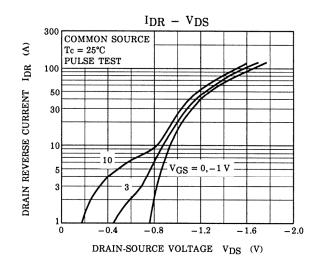


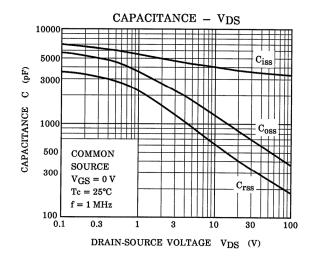


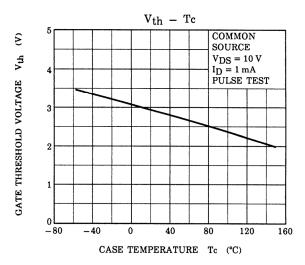


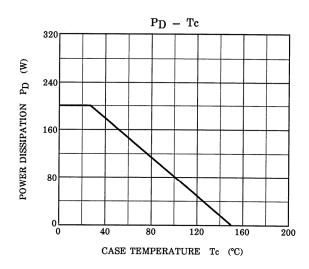


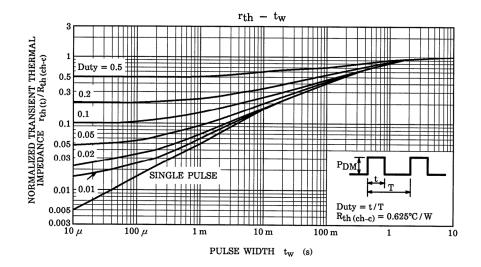


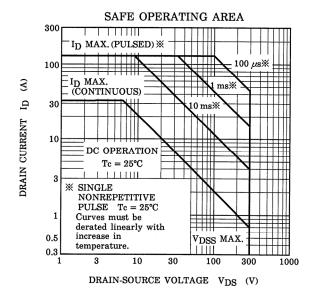












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